



Aliases (C0805S221K2RAC7800)

SMD Comm X7R FE, Ceramic, 220 pF, 10%, 200 VDC, X7R, SMD, MLCC, FE-CAP, Floating Electrode, Temperature Stable, 0805



Click here for the 3D model.

Chip Size 0805   L 2mm +/-0.2mm   W 1.25mm +/-0.2mm   T 0.78mm +/-0.10mm   S 0.75mm MIN   B 0.5mm +/-0.25mm	Dimensions	
W 1.25mm +/-0.2mm   T 0.78mm +/-0.10mm   S 0.75mm MIN	Chip Size	0805
T 0.78mm +/-0.10mm   S 0.75mm MIN	L	2mm +/-0.2mm
S 0.75mm MIN	W	1.25mm +/-0.2mm
	Т	0.78mm +/-0.10mm
B 0.5mm +/-0.25mm	S	0.75mm MIN
	В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm X7R FE
Style	SMD Chip
Description	SMD, MLCC, FE-CAP, Floating Electrode, Temperature Stable
Features	FE-CAP, Floating Electrode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	220 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.